

ATROX® HT900-6B

Electrically and Thermally Conductive Die Attach Adhesive

DESCRIPTION

ATROX HT900-6B is a low stress thermosetting conductive die attach adhesive with high thermal conductivity designed for high power LED packages. **ATROX HT900-6B** has low resin bleed out and low condensable organics which ensure excellent package reliability.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

TYPICAL PROPERTIES

Material Properties	Method	Value	Remarks		
A. Uncured					
Chemical type		Thermosetting			
Color	Visual	Grey			
Viscosity at 25°C at 5.0 RPM	ASTM D2196-99	10,000	Brookfield Spindle 51		
Thixotropic index (0.5 RPM/5.0 RPM)	ASTM D2196-99	5.0	Brookfield Spindle 51		
Pot Life @ 23°C (time to doubling of viscosity)	ISO 10364:1993	>24 hours	Brookfield Spindle 51		
Storage Temperature		-40 (°C/°F)			
Shelf Life @ -40 (°C/°F)		6 months			
B. Cured					
Glass Transition (Tg)	TMA	16 °C			
Modulus at 25 °C	DMA	9.6 GPa			
Modulus at 260 °C	DMA	1.4 GPa			
CTE1(Below Tg)	TMA	65 ppm			
CTE2 (Above Tg)	TMA	113 ppm			
Thermal Conductivity: Bulk Effective	Laser Flash	92 W/mK 44 W/mK			





TECHNICAL DATA SHEET Semiconductor Solutions

Material Properties	Method	Value	Remarks
Volume Resistivity	4-Point probe	0.000025 Ohm-cm	
% Moisture Absorption	72 hrs @ 85%RH/85 °C	0.2%	
Thermal Stability at 300 °C	TGA of cured sample- Ramp to 450 °C	0.3%	

DIE SHEAR STRENGTH (5 mm x 5 mm)

Lead Frame	Cure Condition	Measuring Temperature	Value
Ag	Ramp to 175C in 30 minutes + Hold for 60 minutes at 175C	260°C	11 Kg
NiPdAu (PPF)	Ramp to 175C in 30 minutes + Hold for 60 minutes at 175C	260°C	10 Kg
Cu	Ramp to 175C in 30 minutes + Hold for 60 minutes at 175C	260°C	9 Kg

MATERIAL APPLICATION

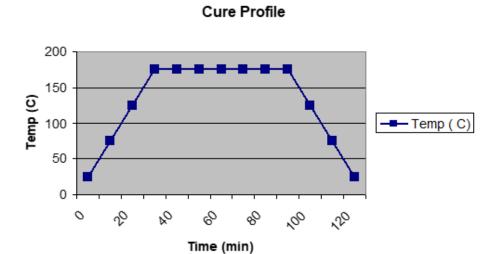
ATROX HT900-6B is formulated to be applied using a time pressure pump equipped on most die bonders. The material should be consistently dispensed over time. Equipment settings need to be optimized for desired material deposition response based on model and configuration.

CURE

ATROX HT900-6B cures using straight ramp cure profile with dwell time of 60 minutes at 175 °C. It is recommended that the cure schedule includes at ramp at 5 to 10 °C and a controlled cooling cycle to minimize thermal stresses. Depending on thermal mass of application cure times may vary and should be optimized by the end user.







RELIABILITY PERFORMANCE

ATROX HT900-6B is recommended for excellent reliability with stable Electrical and Thermal performance during Reliability testing. There is no limitation on die size for metalized OR Bare Silicon die packages. However, it is recommended to consult with your local Technical Service Representative for optimizing critical parameters for specific packages.

For optimum results it is recommended to set the Bond Line Thickness to approximately 1 mil after cure.

CLEAN-UP

Uncured material may be cleaned from dispenser components and surfaces with a variety of solvents, including IPA, acetone, MEK, methylene chloride, etc. Always wash and dry thoroughly prior to re-use of the dispenser components. The cleaning technique should be active cleaning of the components – flush, wash or wipe, followed by a drying step to ensure a clean, dry surface. Do not soak since this can solubilize the hardener within the uncured resin and curing (very difficult to remove). Contact your equipment supplier to ensure the solvent is compatible with their components. Clean and maintain dispense valves as recommended by the equipment manufacturer.

PACKAGING SIZES

ATROX HT900-6B is available in 5 or 10 cc EFD or Musashi syringes.





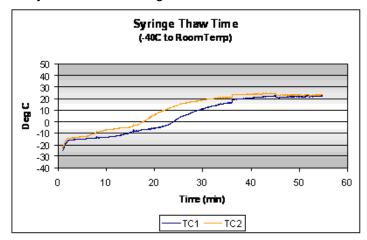
SAFETY & WARNING

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available.**

SHIPPING & STORAGE

Material is normally shipped in insulated boxes using dry ice to ensure that the ATROX HT900-6B maintains all its properties. On receipt, it must be ensured that dry-ice remnants are present in the insulated shipping box. If there is no dry ice, or if the material is not cold, then please contact MacDermid Alpha Electronics Solutions immediately. Exposing to elevated temperatures during shipment and storage will compromise on the performance aspect of the material adversely.

It is recommended to store the syringes of material at -40°C for a maximum shelf life of 6 months. It is recommended that the material be allowed to thaw before usage. Typical thawing times for 5cc and 10cc syringes are presented in chart below. Remove the syringe from freezer and set aside, allowing it to thaw at room temperature, until it reaches room temperature (90 minutes maximum for 30cc syringe). To prevent contamination of unused product, do not return any material to its original container.







TECHNICAL DATA SHEET Semiconductor Solutions

CONTACT INFORMATION

To confirm this document is the most recent version, please contact techinfo@MacDermidAlpha.com

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Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 202, Mexico 91800 021 400 and (55) 5559 1588

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